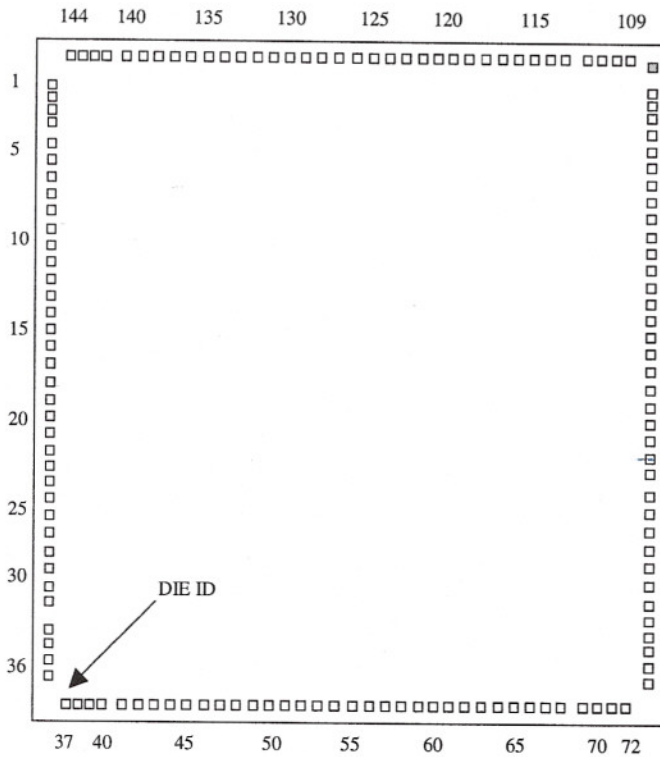




Sierra Components, Inc.

2222 Park Place • Suite 3E • Minden, Nevada 89423
 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



PAD FUNCTIONS

1. A20	42. R / N.W	84. D7	127. N.RESET
2. VSS	43. DVDD	85. D6	128. N.SHZ
3. A19	44. N.IACK	86. DVDD	129. DVDD
4. A18	45. N.RDY	87. D5	130. EXTCLK
5. A17	46. CVDD	88. D4	131. PLLVDD
6. DVDD	47. N.HOLD	89. VSS	132. XOUT
7. A16	48. N.HOLDA	90. D3	133. XIN
8. A15	49. VSS	91. D2	134. PLLVSS
9. VSS	50. D31	92. D1	135. CLKMD1
10. A14	51. D30	93. D0	136. CLKMD0
11. A13	52. D29	94. DVDD	137. CVDD
12. CVDD	53. DVDD	95. EMU1	138. RSV1
13. A12	54. D28	96. EMU0	139. RSV0
14. A11	55. D27	97. VSS	140. VSS
15. DVDD	56. VSS	98. TCK	141. A23
16. A10	57. D26	99. TD0	142. A22
17. A9	58. D25	100. TDI	143. DVDD
18. VSS	59. D24	101. CVDD	144. A21
19. A8	60. DVDD	102. TMS	
20. A7	61. D23	103. N.TRST	
21. A6	62. D22	104. DR0	
22. A5	63. VSS	105. VSS	
23. DVDD	64. D21	106. FSR0	
24. A4	65. D20	107. CLKR0	
25. VSS	66. CVDD	108. DVDD	
26. A3	67. D19	109. CLKX0	
27. A2	68. D18	110. FSX0	
28. CVDD	69. DVDD	111. DX0	
29. A1	70. D17	112. VSS	
30. A0	71. D16	113. TCLK1	
31. DVDD	72. VSS	114. TCLK0	
32. N. PAGE3	73. D15	115. DVDD	
33. N. PAGE2	74. D14	116. XF1	
34. VSS	75. D13	117. XF0	
35. N. PAGE1	76. D12	118. VSS	
36. N. PAGE0	77. DVDD	119. N.INT3	
37. DVDD	78. D11	120. N.INT2	
38. H1	79. D10	121. N.INT1	
39. H3	80. VSS	122. N.INT0	
40. VSS	81. D9	123. CVDD	
41. N.STRB	82. D8	124. EDGEMODE	
	83. CVDD	125. MCBL /N.MP	
		126. VSS	

The information given is believed to be correct at the time of issue.

Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.

Back potential is the electrical potential of the substrate (bulk silicon) which does not require an electrical connection unless stated in this drawing.

Topside Metal: Aluminum
Backside Metal: Silicon Nitride
Backside Potential:
Bond Pad Size: .004" min.
Mask Ref:

APPROVED BY: C Dawson

DIE SIZE : .198" X .216 "

DATE: 3/31/10

MFG: Texas Inst

THICKNESS: .025"

Part # TMS320VC33PGEA120UC1524A